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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	28KB (16K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SSOP (0.209", 5.30mm Width)
Supplier Device Package	28-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1938-e-ss

TABLE 3-10: SPECIAL FUNCTION REGISTER SUMMARY (CONTINUED)

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
Bank 8											
400h(2)	INDF0	Addressing this location uses contents of FSR0H/FSR0L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
401h(2)	INDF1	Addressing this location uses contents of FSR1H/FSR1L to address data memory (not a physical register)								xxxx xxxx	xxxx xxxx
402h(2)	PCL	Program Counter (PC) Least Significant Byte								0000 0000	0000 0000
403h(2)	STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	---1 1000	---q quuu
404h(2)	FSR0L	Indirect Data Memory Address 0 Low Pointer								0000 0000	uuuu uuuu
405h(2)	FSR0H	Indirect Data Memory Address 0 High Pointer								0000 0000	0000 0000
406h(2)	FSR1L	Indirect Data Memory Address 1 Low Pointer								0000 0000	uuuu uuuu
407h(2)	FSR1H	Indirect Data Memory Address 1 High Pointer								0000 0000	0000 0000
408h(2)	BSR	—	—	—	BSR<4:0>					---0 0000	---0 0000
409h(2)	WREG	Working Register								0000 0000	uuuu uuuu
40Ah(1, 2)	PCLATH	—	Write Buffer for the upper 7 bits of the Program Counter							-000 0000	-000 0000
40Bh(2)	INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	0000 0000	0000 0000
40Ch	—	Unimplemented								—	—
40Dh	—	Unimplemented								—	—
40Eh	—	Unimplemented								—	—
40Fh	—	Unimplemented								—	—
410h	—	Unimplemented								—	—
411h	—	Unimplemented								—	—
412h	—	Unimplemented								—	—
413h	—	Unimplemented								—	—
414h	—	Unimplemented								—	—
415h	TMR4	Timer 4 Module Register								0000 0000	0000 0000
416h	PR4	Timer 4 Period Register								1111 1111	1111 1111
417h	T4CON	—	T4OUTPS<3:0>				TMR4ON	T4CKPS<1:0>		-000 0000	-000 0000
418h	—	Unimplemented								—	—
419h	—	Unimplemented								—	—
41Ah	—	Unimplemented								—	—
41Bh	—	Unimplemented								—	—
41Ch	TMR6	Timer 6 Module Register								0000 0000	0000 0000
41Dh	PR6	Timer 6 Period Register								1111 1111	1111 1111
41Eh	T6CON	—	T6OUTPS<3:0>				TMR6ON	T6CKPS<1:0>		-000 0000	-000 0000
41Fh	—	Unimplemented								—	—

Legend: x = unknown, u = unchanged, q = value depends on condition, - = unimplemented, read as '0', r = reserved. Shaded locations are unimplemented, read as '0'.

Note 1: The upper byte of the program counter is not directly accessible. PCLATH is a holding register for the PC<14:8>, whose contents are transferred to the upper byte of the program counter.

2: These registers can be addressed from any bank.

3: These registers/bits are not implemented on PIC16(L)F1938 devices, read as '0'.

4: Unimplemented, read as '1'.

5.6 Register Definitions: Oscillator Control

REGISTER 5-1: OSCCON: OSCILLATOR CONTROL REGISTER

R/W-0/0	R/W-0/0	R/W-1/1	R/W-1/1	R/W-1/1	U-0	R/W-0/0	R/W-0/0
SPLLEN	IRCF<3:0>				—	SCS<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **SPLLEN:** Software PLL Enable bit
If PLLEN in Configuration Words = 1:
SPLLEN bit is ignored. 4x PLL is always enabled (subject to oscillator requirements)
If PLLEN in Configuration Words = 0:
1 = 4x PLL Is enabled
0 = 4x PLL is disabled

bit 6-3 **IRCF<3:0>:** Internal Oscillator Frequency Select bits
1111 = 16 MHz HF
1110 = 8 MHz or 32 MHz HF (see **Section 5.2.2.1 "HFINTOSC"**)
1101 = 4 MHz HF
1100 = 2 MHz HF
1011 = 1 MHz HF
1010 = 500 kHz HF(1)
1001 = 250 kHz HF(1)
1000 = 125 kHz HF(1)
0111 = 500 kHz MF (default upon Reset)
0110 = 250 kHz MF
0101 = 125 kHz MF
0100 = 62.5 kHz MF
0011 = 31.25 kHz HF(1)
0010 = 31.25 kHz MF
000x = 31 kHz LF

bit 2 **Unimplemented:** Read as '0'

bit 1-0 **SCS<1:0>:** System Clock Select bits
1x = Internal oscillator block
01 = Timer1 oscillator
00 = Clock determined by FOSC<2:0> in Configuration Words.

Note 1: Duplicate frequency derived from HFINTOSC.

6.0 RESETS

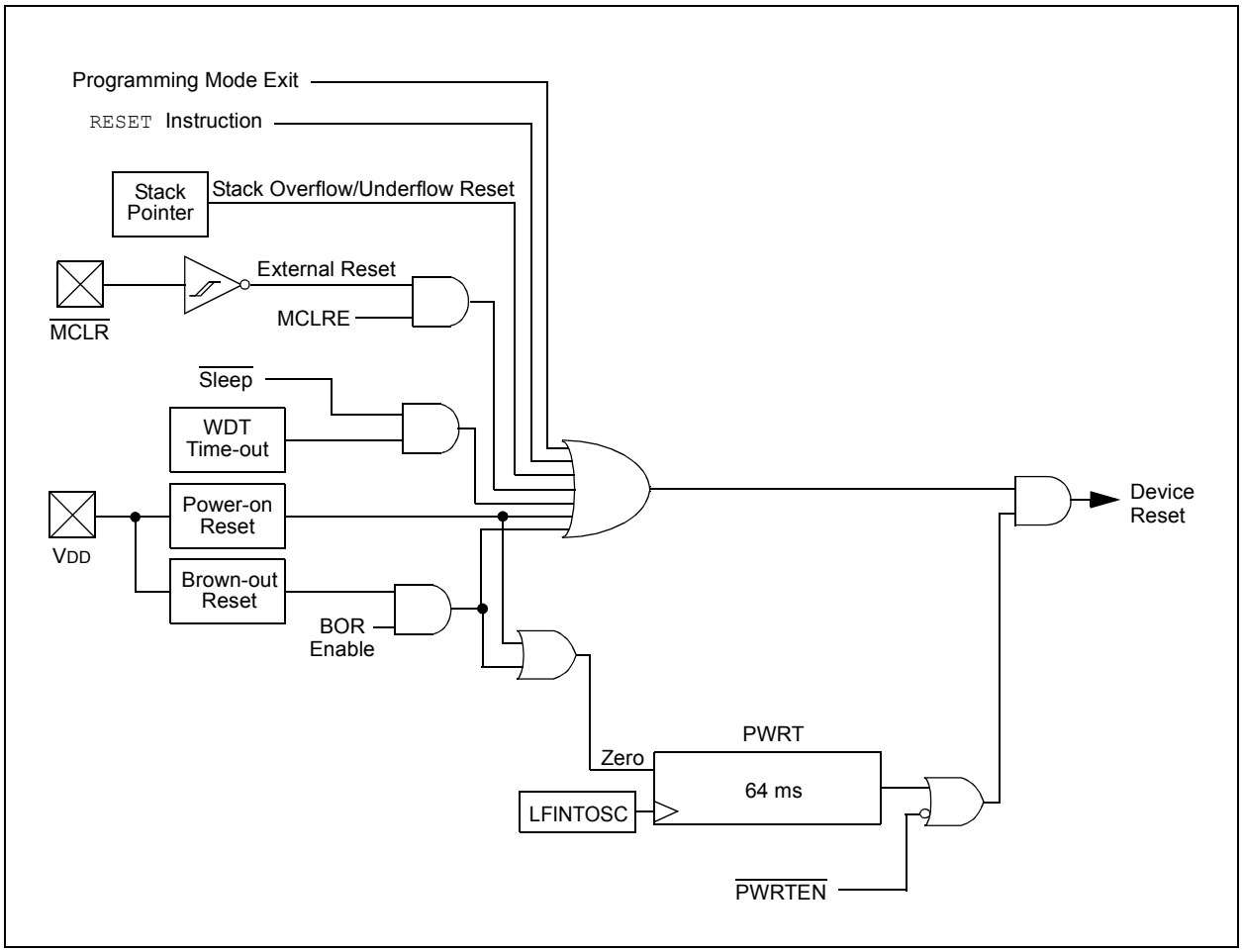
There are multiple ways to reset this device:

- Power-on Reset (POR)
- Brown-out Reset (BOR)
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional power-up timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 6-1.

FIGURE 6-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



11.3.2 ERASING FLASH PROGRAM MEMORY

While executing code, program memory can only be erased by rows. To erase a row:

1. Load the EEADRH:EEADRL register pair with the address of new row to be erased.
2. Clear the CFGS bit of the EECON1 register.
3. Set the EEPGD, FREE, and WREN bits of the EECON1 register.
4. Write 55h, then AAh, to EECON2 (Flash programming unlock sequence).
5. Set control bit WR of the EECON1 register to begin the erase operation.
6. Poll the FREE bit in the EECON1 register to determine when the row erase has completed.

See Example 11-4.

After the "`BSF EECON1,WR`" instruction, the processor requires two cycles to set up the erase operation. The user must place two `NOP` instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms erase time. This is not Sleep mode as the clocks and peripherals will continue to run. After the erase cycle, the processor will resume operation with the third instruction after the EECON1 write instruction.

11.3.3 WRITING TO FLASH PROGRAM MEMORY

Program memory is programmed using the following steps:

1. Load the starting address of the word(s) to be programmed.
2. Load the write latches with data.
3. Initiate a programming operation.
4. Repeat steps 1 through 3 until all data is written.

Before writing to program memory, the word(s) to be written must be erased or previously unwritten. Program memory can only be erased one row at a time. No automatic erase occurs upon the initiation of the write.

Program memory can be written one or more words at a time. The maximum number of words written at one time is equal to the number of write latches. See Figure 11-2 (block writes to program memory with 8 write latches) for more details. The write latches are aligned to the address boundary defined by EEADRL as shown in Table 11-1. Write operations do not cross these boundaries. At the completion of a program memory write operation, the write latches are reset to contain 0x3FFF.

The following steps should be completed to load the write latches and program a block of program memory. These steps are divided into two parts. First, all write latches are loaded with data except for the last program memory location. Then, the last write latch is loaded and the programming sequence is initiated. A special unlock sequence is required to load a write latch with data or initiate a Flash programming operation. This unlock sequence should not be interrupted.

1. Set the EEPGD and WREN bits of the EECON1 register.
2. Clear the CFGS bit of the EECON1 register.
3. Set the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '`1`', the write sequence will only load the write latches and will not initiate the write to Flash program memory.
4. Load the EEADRH:EEADRL register pair with the address of the location to be written.
5. Load the EEDATH:EEDATL register pair with the program memory data to be written.
6. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The write latch is now loaded.
7. Increment the EEADRH:EEADRL register pair to point to the next location.
8. Repeat steps 5 through 7 until all but the last write latch has been loaded.
9. Clear the LWLO bit of the EECON1 register. When the LWLO bit of the EECON1 register is '`0`', the write sequence will initiate the write to Flash program memory.
10. Load the EEDATH:EEDATL register pair with the program memory data to be written.
11. Write 55h, then AAh, to EECON2, then set the WR bit of the EECON1 register (Flash programming unlock sequence). The entire latch block is now written to Flash program memory.

It is not necessary to load the entire write latch block with user program data. However, the entire write latch block will be written to program memory.

An example of the complete write sequence for eight words is shown in Example 11-5. The initial address is loaded into the EEADRH:EEADRL register pair; the eight words of data are loaded using indirect addressing.

Note:	The code sequence provided in Example 11-5 must be repeated multiple times to fully program an erased program memory row.

15.1 ADC Configuration

When configuring and using the ADC the following functions must be considered:

- Port configuration
- Channel selection
- ADC voltage reference selection
- ADC conversion clock source
- Interrupt control
- Result formatting

15.1.1 PORT CONFIGURATION

The ADC can be used to convert both analog and digital signals. When converting analog signals, the I/O pin should be configured for analog by setting the associated TRIS and ANSEL bits. Refer to **Section 12.0 "I/O Ports"** for more information.

Note:	Analog voltages on any pin that is defined as a digital input may cause the input buffer to conduct excess current.

15.1.2 CHANNEL SELECTION

There are up to 17 channel selections available:

- AN<13:0> pins
- Temperature Indicator
- DAC Output
- FVR (Fixed Voltage Reference) Output

Refer to **Section 16.0 "Temperature Indicator Module"**, **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** and **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on these channel selections.

The CHS bits of the ADCON0 register determine which channel is connected to the sample and hold circuit.

When changing channels, a delay is required before starting the next conversion. Refer to **Section 15.2 "ADC Operation"** for more information.

15.1.3 ADC VOLTAGE REFERENCE

The ADPREF bits of the ADCON1 register provides control of the positive voltage reference. The positive voltage reference can be:

- VREF+ pin
- VDD

The ADNREF bits of the ADCON1 register provides control of the negative voltage reference. The negative voltage reference can be:

- VREF- pin
- VSS

See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more details on the fixed voltage reference.

15.1.4 CONVERSION CLOCK

The source of the conversion clock is software selectable via the ADCS bits of the ADCON1 register. There are seven possible clock options:

- FOSC/2
- FOSC/4
- FOSC/8
- FOSC/16
- FOSC/32
- FOSC/64
- FRC (dedicated internal oscillator)

The time to complete one bit conversion is defined as TAD. One full 10-bit conversion requires 11.5 TAD periods as shown in Figure 15-2.

For correct conversion, the appropriate TAD specification must be met. Refer to the A/D conversion requirements in the applicable Electrical Specifications Chapter for more information. Table 15-1 gives examples of appropriate ADC clock selections.

Note:	Unless using the FRC, any changes in the system clock frequency will change the ADC clock frequency, which may adversely affect the ADC result.

15.3 Register Definitions: ADC Control

REGISTER 15-1: ADCON0: A/D CONTROL REGISTER 0

U-0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0
—	CHS<4:0>					GO/$\overline{\text{DONE}}$	ADON
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **Unimplemented:** Read as '0'

bit 6-2 **CHS<4:0>:** Analog Channel Select bits

11111 = FVR (Fixed Voltage Reference) Buffer 1 Output(2)
11110 = DAC output(1)
11101 = Temperature Indicator(3)
11100 = Reserved. No channel connected.
•
•
•
01110 = Reserved. No channel connected.
01101 = AN13
01100 = AN12
01011 = AN11
01010 = AN10
01001 = AN9
01000 = AN8
00111 = AN7(4)
00110 = AN6(4)
00101 = AN5(4)
00100 = AN4
00011 = AN3
00010 = AN2
00001 = AN1
00000 = AN0

bit 1 **GO/$\overline{\text{DONE}}$:** A/D Conversion Status bit

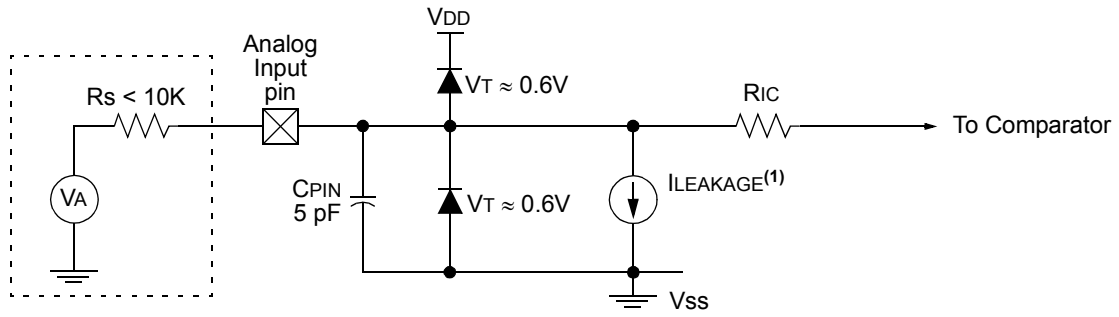
1 = A/D conversion cycle in progress. Setting this bit starts an A/D conversion cycle.
This bit is automatically cleared by hardware when the A/D conversion has completed.
0 = A/D conversion completed/not in progress

bit 0 **ADON:** ADC Enable bit

1 = ADC is enabled
0 = ADC is disabled and consumes no operating current

Note 1: See **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** for more information.
2: See **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information.
3: See **Section 16.0 "Temperature Indicator Module"** for more information.
4: Not available on the PIC16(L)F1933/1936/1938.

FIGURE 18-3: ANALOG INPUT MODEL



Legend: CPIN = Input Capacitance
ILEAKAGE = Leakage Current at the pin due to various junctions
RIC = Interconnect Resistance
RS = Source Impedance
VA = Analog Voltage
VT = Threshold Voltage

Note 1: See **Section 30.0 "Electrical Specifications"**.

24.6.5 I²C MASTER MODE REPEATED START CONDITION TIMING

A Repeated Start condition occurs when the RSEN bit of the SSPCON2 register is programmed high and the Master state machine is no longer active. When the RSEN bit is set, the SCL pin is asserted low. When the SCL pin is sampled low, the Baud Rate Generator is loaded and begins counting. The SDA pin is released (brought high) for one Baud Rate Generator count (TBRG). When the Baud Rate Generator times out, if SDA is sampled high, the SCL pin will be deasserted (brought high). When SCL is sampled high, the Baud Rate Generator is reloaded and begins counting. SDA and SCL must be sampled high for one TBRG. This action is then followed by assertion of the SDA pin (SDA = 0) for one TBRG while SCL is high. SCL is asserted low. Following this, the RSEN bit of the SSPCON2 register will be automatically cleared and the Baud Rate Generator will not be reloaded, leaving the SDA pin held low. As soon as a Start condition is detected on the SDA and SCL pins, the S bit of the SSPSTAT register will be set. The SSPIF bit will not be set until the Baud Rate Generator has timed out.

Note 1: If RSEN is programmed while any other event is in progress, it will not take effect.

2: A bus collision during the Repeated Start condition occurs if:

- SDA is sampled low when SCL goes from low-to-high.
- SCL goes low before SDA is asserted low. This may indicate that another master is attempting to transmit a data '1'.

FIGURE 24-27: REPEAT START CONDITION WAVEFORM

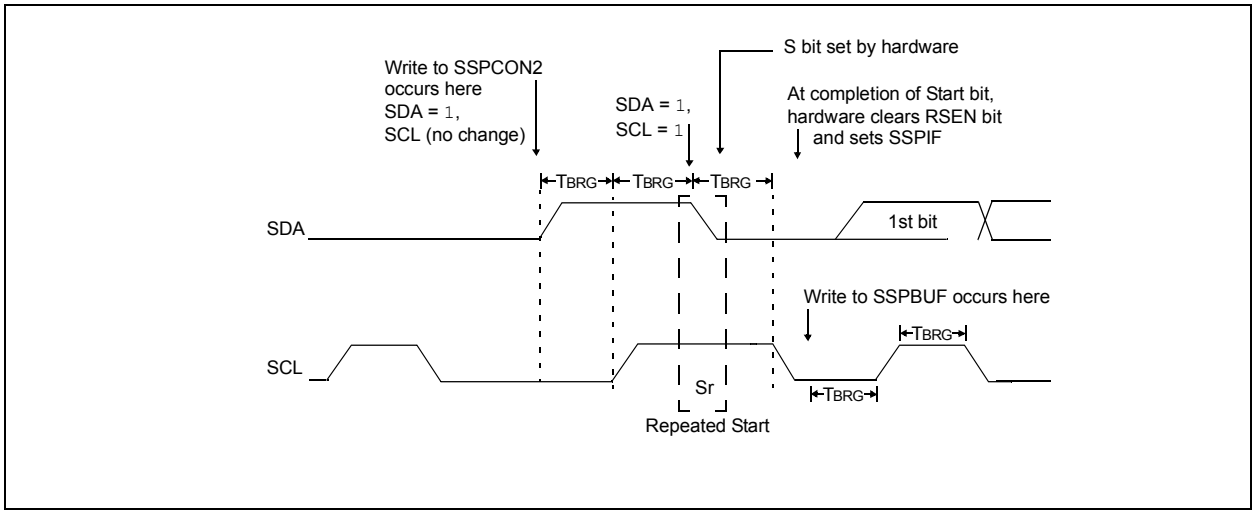
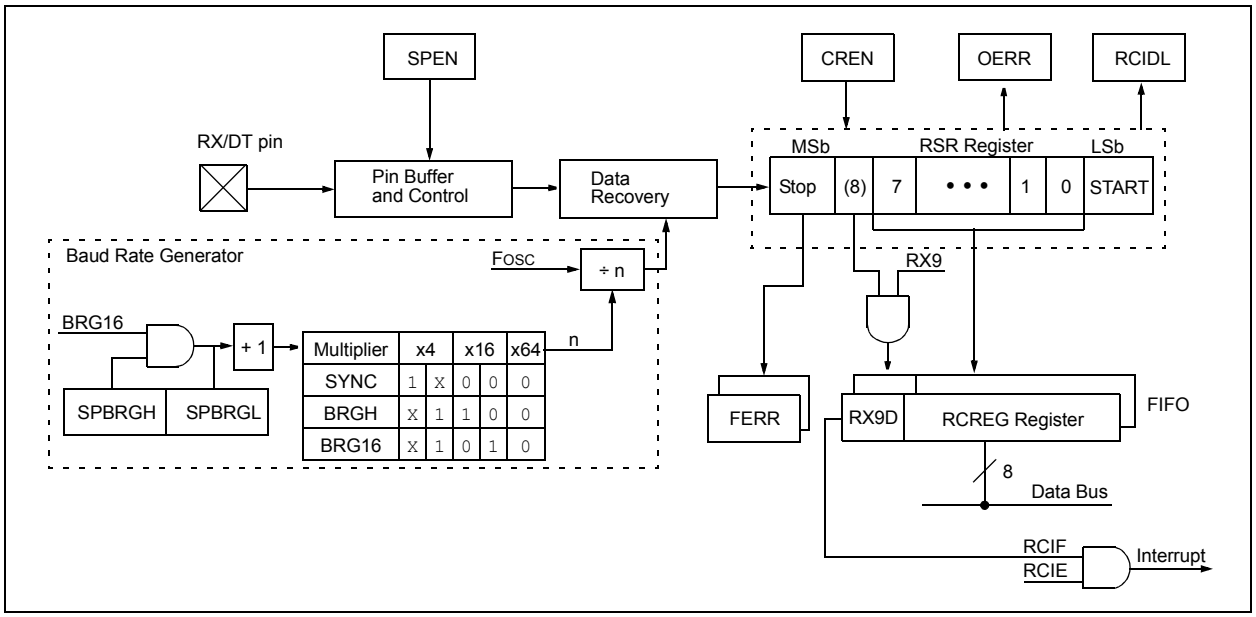


FIGURE 25-2: EUSART RECEIVE BLOCK DIAGRAM



The operation of the EUSART module is controlled through three registers:

- Transmit Status and Control (TXSTA)
- Receive Status and Control (RCSTA)
- Baud Rate Control (BAUDCON)

These registers are detailed in Register 25-1, Register 25-2 and Register 25-3, respectively.

When the receiver or transmitter section is not enabled then the corresponding RX or TX pin may be used for general purpose input and output.

25.5.1.5 Synchronous Master Reception

Data is received at the RX/DT pin. The RX/DT pin output driver is automatically disabled when the EUSART is configured for synchronous master receive operation.

In Synchronous mode, reception is enabled by setting either the Single Receive Enable bit (SREN of the RCSTA register) or the Continuous Receive Enable bit (CREN of the RCSTA register).

When SREN is set and CREN is clear, only as many clock cycles are generated as there are data bits in a single character. The SREN bit is automatically cleared at the completion of one character. When CREN is set, clocks are continuously generated until CREN is cleared. If CREN is cleared in the middle of a character the CK clock stops immediately and the partial character is discarded. If SREN and CREN are both set, then SREN is cleared at the completion of the first character and CREN takes precedence.

To initiate reception, set either SREN or CREN. Data is sampled at the RX/DT pin on the trailing edge of the TX/CK clock pin and is shifted into the Receive Shift Register (RSR). When a complete character is received into the RSR, the RCIF bit is set and the character is automatically transferred to the two character receive FIFO. The Least Significant eight bits of the top character in the receive FIFO are available in RCREG. The RCIF bit remains set as long as there are unread characters in the receive FIFO.

25.5.1.6 Slave Clock

Synchronous data transfers use a separate clock line, which is synchronous with the data. A device configured as a slave receives the clock on the TX/CK line. The TX/CK pin output driver is automatically disabled when the device is configured for synchronous slave transmit or receive operation. Serial data bits change on the leading edge to ensure they are valid at the trailing edge of each clock. One data bit is transferred for each clock cycle. Only as many clock cycles should be received as there are data bits.

25.5.1.7 Receive Overrun Error

The receive FIFO buffer can hold two characters. An overrun error will be generated if a third character, in its entirety, is received before RCREG is read to access the FIFO. When this happens the OERR bit of the RCSTA register is set. Previous data in the FIFO will not be overwritten. The two characters in the FIFO buffer can be read, however, no additional characters will be received until the error is cleared. The OERR bit can only be cleared by clearing the overrun condition. If the overrun error occurred when the SREN bit is set and CREN is clear then the error is cleared by reading RCREG. If the overrun occurred when the CREN bit is set then the error condition is cleared by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

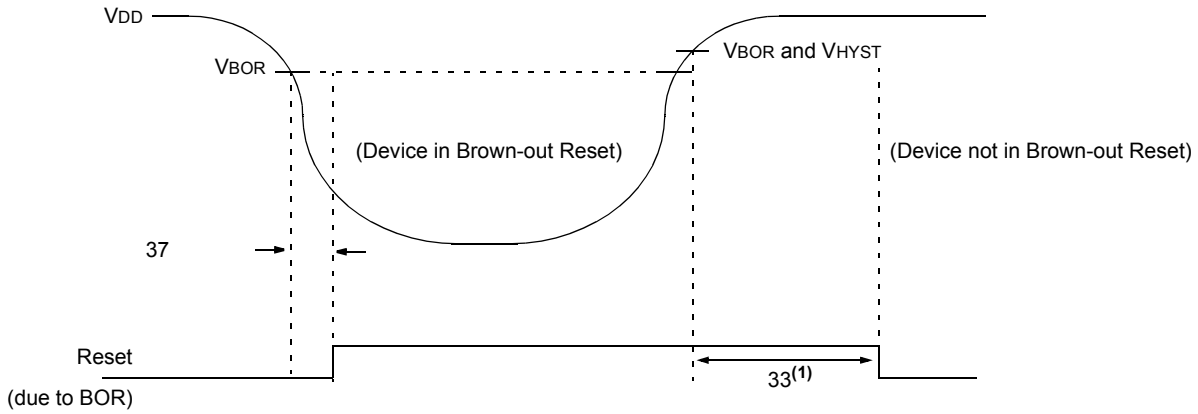
25.5.1.8 Receiving 9-bit Characters

The EUSART supports 9-bit character reception. When the RX9 bit of the RCSTA register is set the EUSART will shift nine bits into the RSR for each character received. The RX9D bit of the RCSTA register is the ninth, and Most Significant, data bit of the top unread character in the receive FIFO. When reading 9-bit data from the receive FIFO buffer, the RX9D data bit must be read before reading the eight Least Significant bits from the RCREG.

25.5.1.9 Synchronous Master Reception Set-up:

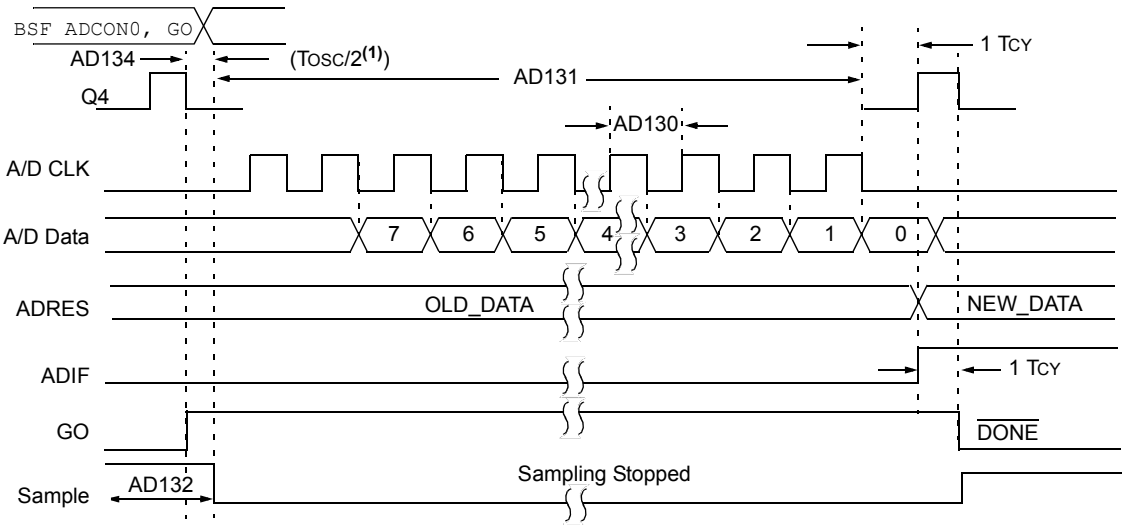
1. Initialize the SPBRGH, SPBRGL register pair for the appropriate baud rate. Set or clear the BRGH and BRG16 bits, as required, to achieve the desired baud rate.
2. Clear the ANSEL bit for the RX pin (if applicable).
3. Enable the synchronous master serial port by setting bits SYNC, SPEN and CSRC.
4. Ensure bits CREN and SREN are clear.
5. If interrupts are desired, set the RCIE bit of the PIE1 register and the GIE and PEIE bits of the INTCON register.
6. If 9-bit reception is desired, set bit RX9.
7. Start reception by setting the SREN bit or for continuous reception, set the CREN bit.
8. Interrupt flag bit RCIF will be set when reception of a character is complete. An interrupt will be generated if the enable bit RCIE was set.
9. Read the RCSTA register to get the ninth bit (if enabled) and determine if any error occurred during reception.
10. Read the 8-bit received data by reading the RCREG register.
11. If an overrun error occurs, clear the error by either clearing the CREN bit of the RCSTA register or by clearing the SPEN bit which resets the EUSART.

FIGURE 30-9: BROWN-OUT RESET TIMING AND CHARACTERISTICS



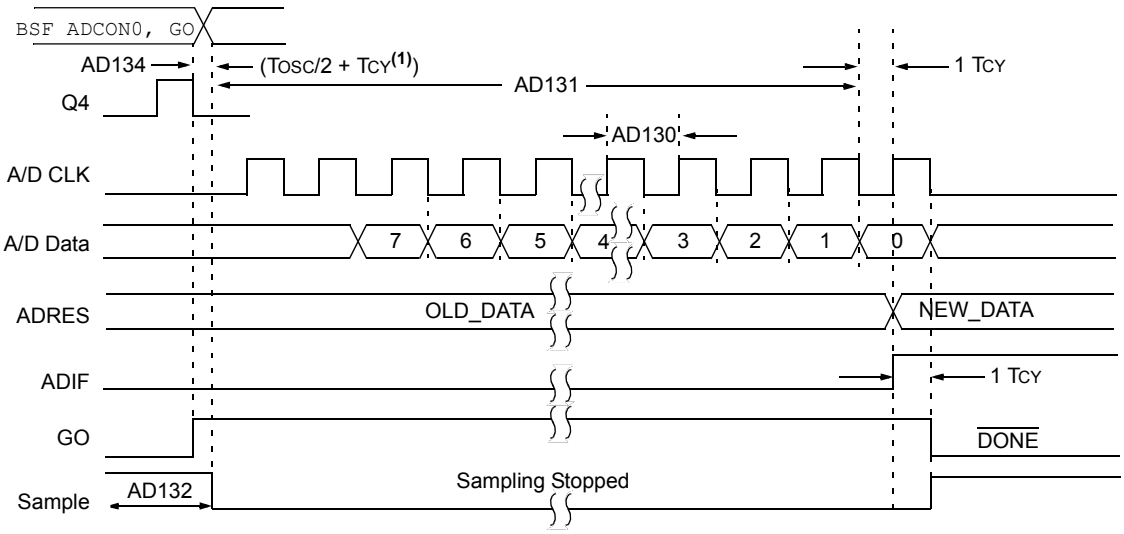
Note 1: 64 ms delay only if $\overline{\text{PWRTE}}$ bit in the Configuration Word register is programmed to '0'.
2 ms delay if $\overline{\text{PWRTE}}$ = 0.

FIGURE 30-12: PIC16(L)F1938/39 A/D CONVERSION TIMING (NORMAL MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

FIGURE 30-13: PIC16(L)F1938/39 A/D CONVERSION TIMING (SLEEP MODE)



Note 1: If the A/D clock source is selected as RC, a time of TCY is added before the A/D clock starts. This allows the SLEEP instruction to be executed.

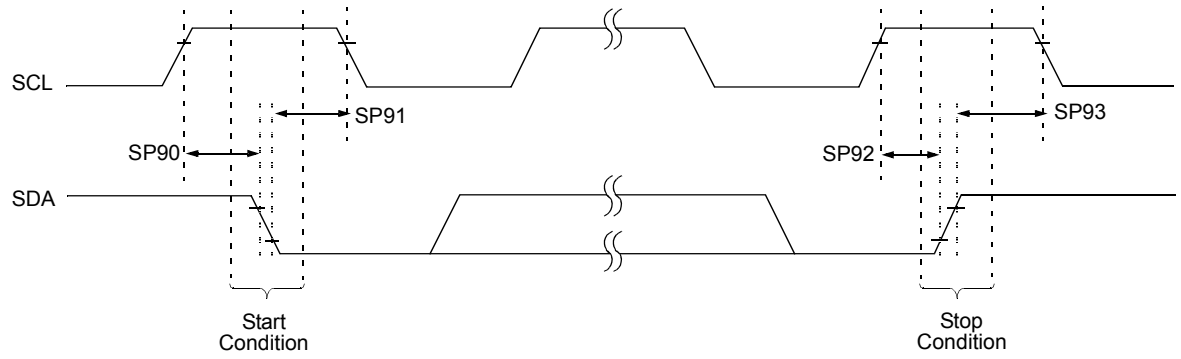
TABLE 30-14: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ†	Max.	Units	Conditions
SP70*	TssL2scH, TssL2scL	$\overline{SS}$↓ to SCK↓ or SCK↑ input		Tcy	—	—	ns	
SP71*	TscH	SCK input high time (Slave mode)		Tcy + 20	—	—	ns	
SP72*	TscL	SCK input low time (Slave mode)		Tcy + 20	—	—	ns	
SP73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
SP74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
SP75*	TdoR	SDO data output rise time	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP76*	TdoF	SDO data output fall time		—	10	25	ns	
SP77*	TssH2doZ	$\overline{SS}$↑ to SDO output high-impedance		10	—	50	ns	
SP78*	TscR	SCK output rise time (Master mode)	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP79*	TscF	SCK output fall time (Master mode)		—	10	25	ns	
SP80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	3.0-5.5V	—	—	50	ns	
			1.8-5.5V	—	—	145	ns	
SP81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	
SP82*	TssL2doV	SDO data output valid after $\overline{SS}$↓ edge		—	—	50	ns	
SP83*	TscH2ssH, TscL2ssH	$\overline{SS}$ ↑ after SCK edge		1.5Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 30-20: I²C™ BUS START/STOP BITS TIMING



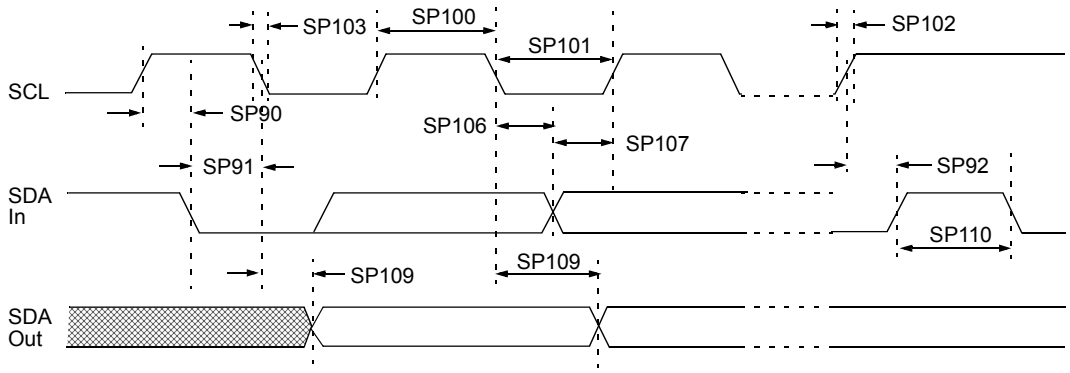
Note: Refer to Figure 30-5 for load conditions.

TABLE 30-15: I²C™ BUS START/STOP BITS REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ	Max.	Units	Conditions
SP90*	TSU:STA	Start condition Setup time	100 kHz mode	4700	—	—	ns	Only relevant for Repeated Start condition
			400 kHz mode	600	—	—		
SP91*	THD:STA	Start condition Hold time	100 kHz mode	4000	—	—	ns	After this period, the first clock pulse is generated
			400 kHz mode	600	—	—		
SP92*	TSU:STO	Stop condition Setup time	100 kHz mode	4700	—	—	ns	
			400 kHz mode	600	—	—		
SP93	THD:STO	Stop condition Hold time	100 kHz mode	4000	—	—	ns	
			400 kHz mode	600	—	—		

* These parameters are characterized but not tested.

FIGURE 30-21: I²C™ BUS DATA TIMING



Note: Refer to Figure 30-5 for load conditions.

FIGURE 31-53: VOH VS. IOH OVER TEMPERATURE, VDD = 3.0V

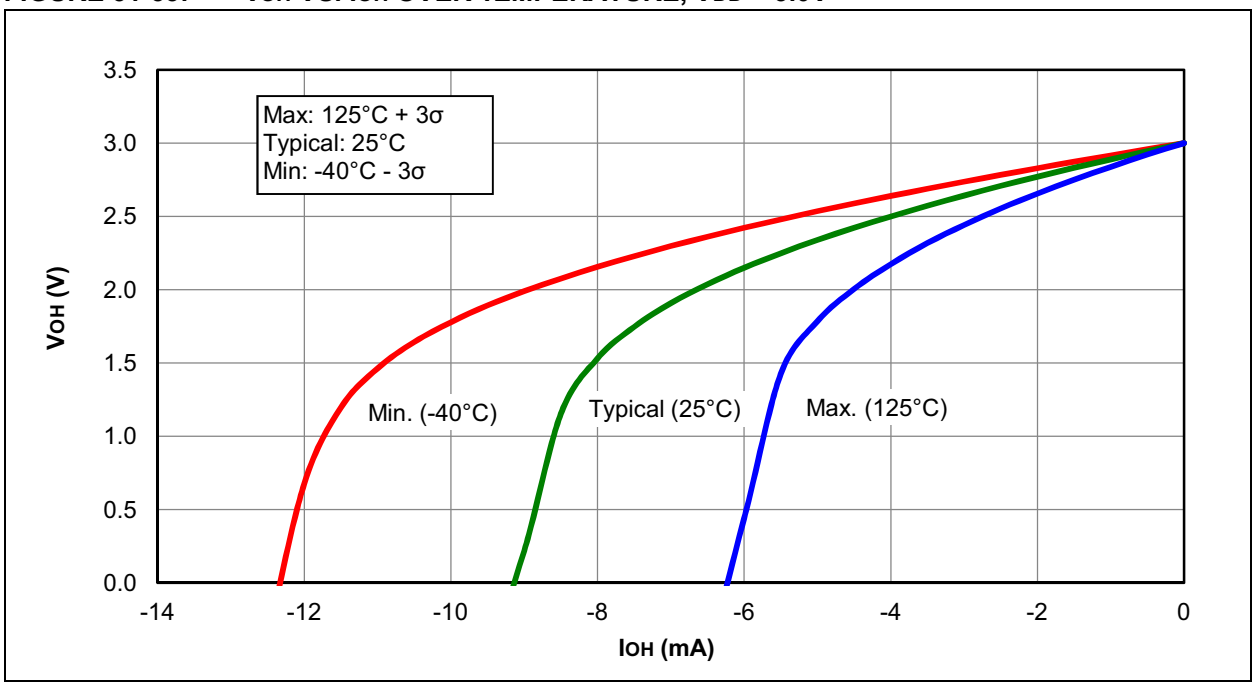
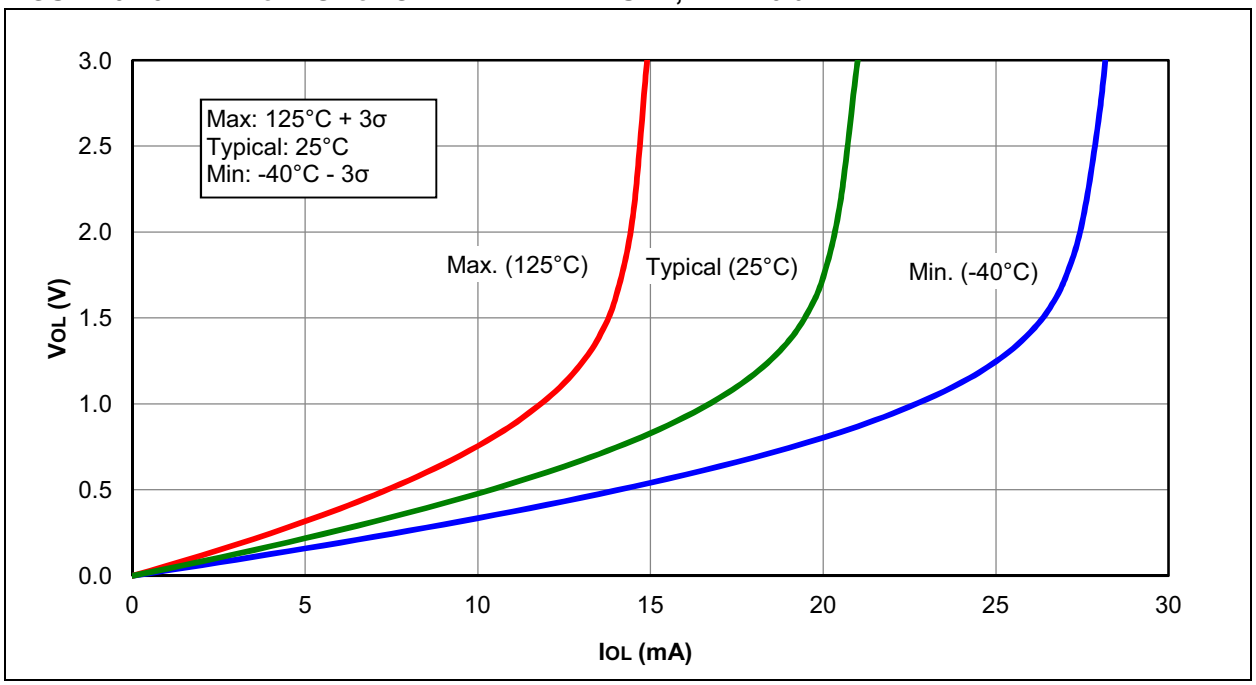


FIGURE 31-54: VOL VS. IOL OVER TEMPERATURE, VDD = 3.0V



32.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

32.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

32.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

32.9 PICkit 3 In-Circuit Debugger/ Programmer

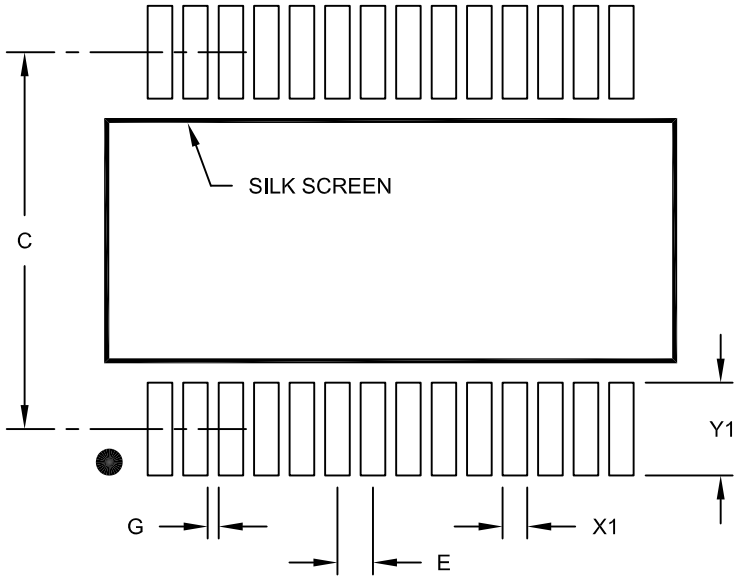
The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

32.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Contact Pad Spacing	C		7.20	
Contact Pad Width (X28)	X1			0.45
Contact Pad Length (X28)	Y1			1.75
Distance Between Pads	G	0.20		

Notes:

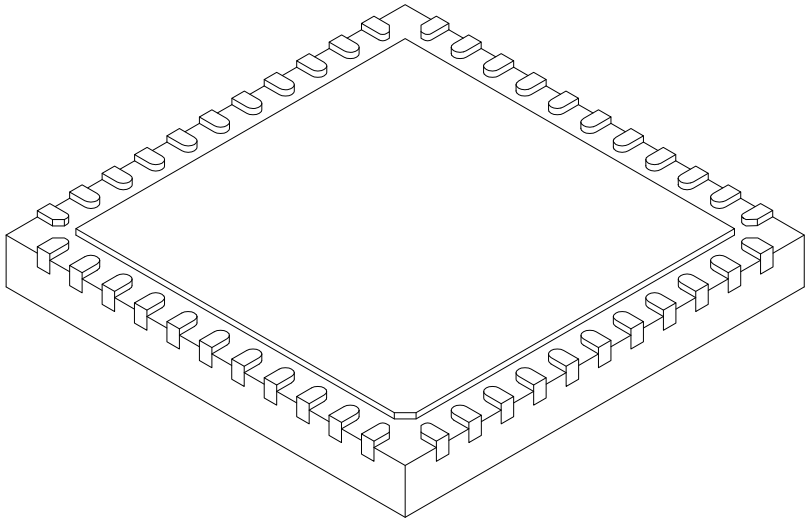
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		44	
Pitch	e		0.65 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Terminal Thickness	A3		0.20 REF	
Overall Width	E		8.00 BSC	
Exposed Pad Width	E2	6.25	6.45	6.60
Overall Length	D		8.00 BSC	
Exposed Pad Length	D2	6.25	6.45	6.60
Terminal Width	b	0.20	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal-to-Exposed-Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103C Sheet 2 of 2

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	[X](1)	-	X	/XX	XXX
Device	Tape and Reel Option		Temperature Range	Package	Pattern

Device:	PIC16F1938, PIC16LF1938 PIC16F1939, PIC16LF1939
Tape and Reel Option:	Blank = Standard packaging (tube or tray) T = Tape and Reel(1)
Temperature Range:	I = -40°C to +85°C E = -40°C to +125°C
Package:	ML = QFN MV = UQFN P = PDIP PT = TQFP SO = SOIC SP = SPDIP SS = SSOP
Pattern:	3-Digit Pattern Code for QTP (blank otherwise)

Examples:

a) PIC16LF1938 - I/P = Industrial temp., Plastic DIP package, low-voltage V_{DD} limits.

b) PIC16F1939 - I/PT = Industrial temp., TQFP package, standard V_{DD} limits.

c) PIC16F1939 - E/ML = Extended temp., QFN package, standard V_{DD} limits.

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.

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